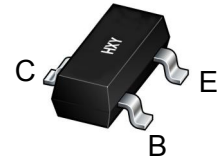




FEATURES

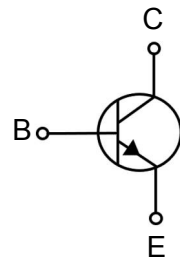
- Collector Current: $I_C=0.2A$
- Power Dissipation of 350mw



SOT-23

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MMBTA44	SOT-23	3D	3000



MAXIMUM RATINGS (Ta=25 unless otherwise noted)

Parameter	Symbol	Limit	Unit
Collector-Base Voltage	V_{CBO}	350	V
Collector-Emitter Voltage	V_{CEO}	350	V
Emitter-Base Voltage	V_{EBO}	6	V
Collector Current	I_C	200	mA
Collector Power Dissipation	P_C	350	mW
Thermal Resistance From Junction To Ambient	$R_{\theta JA}$	357	$^{\circ}C/W$
Junction Temperature	T_J	150	$^{\circ}C$
Storage Temperature	T_{stg}	-55~+150	$^{\circ}C$

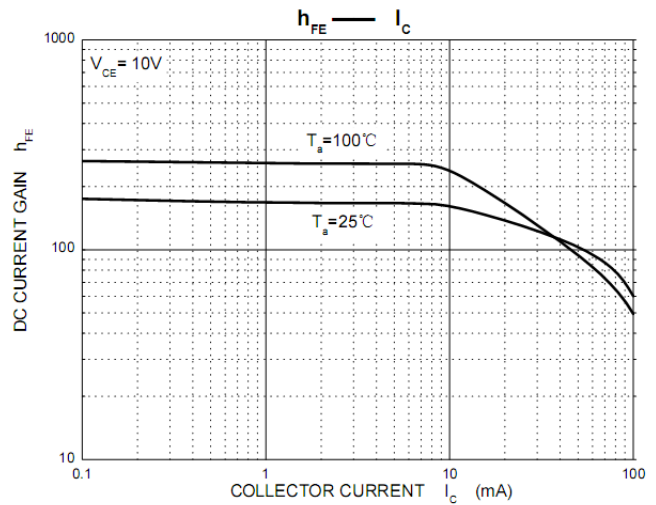
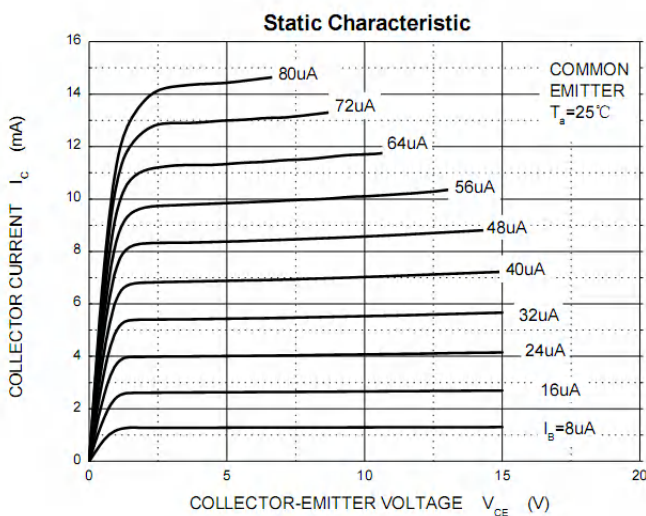


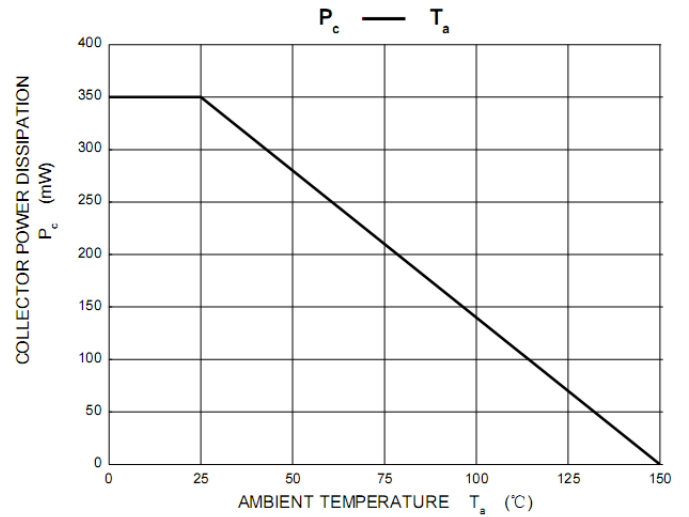
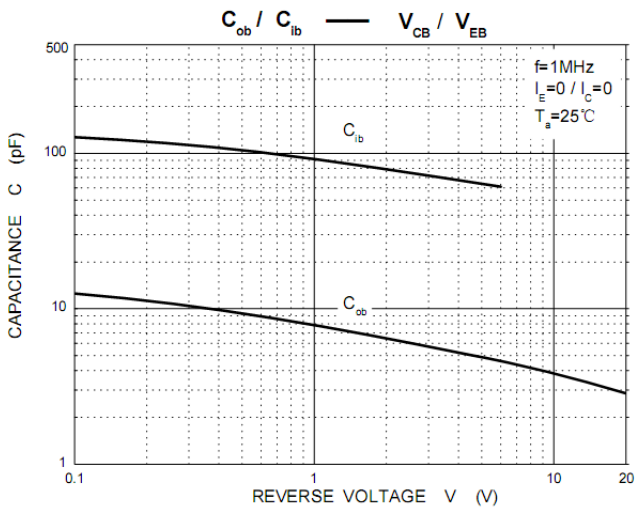
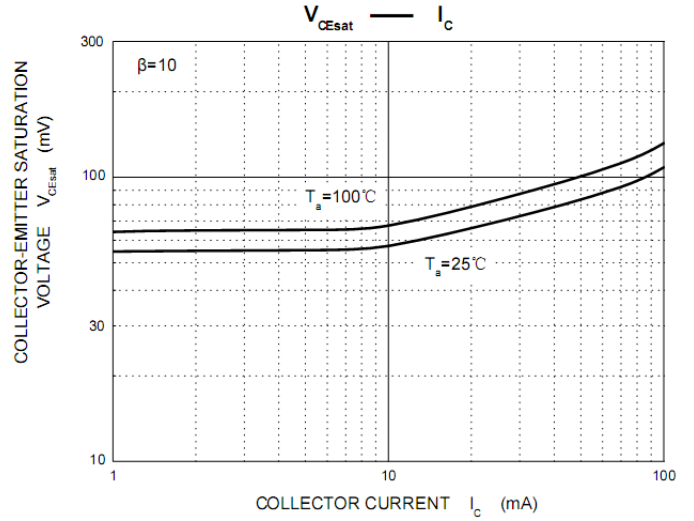
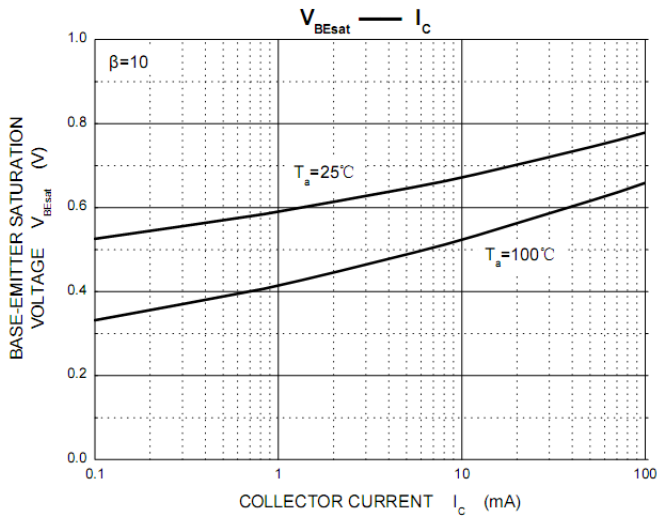
ELECTRICAL CHARACTERISTICS (T_a=25 unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Collector-base breakdown voltage	V _{(BR)CBO}	I _C =100μA, I _E =0	350			V
Collector-emitter breakdown voltage	V _{(BR)CEO} *	I _C =1mA, I _B =0	350			V
Emitter-base breakdown voltage	V _{(BR)EBO}	I _E =10μA, I _C =0	6			V
Collector cut-off current	I _{CBO}	V _{CB} =300V, I _E =0			0.1	μA
Emitter cut-off current	I _{EBO}	V _{EB} =4V, I _C =0			0.1	μA
DC current gain	h _{FE(1)} *	V _{CE} =10V, I _C =1mA	40			
	h _{FE(2)} *	V _{CE} =10V, I _C =10mA	50		200	
	h _{FE(3)} *	V _{CE} =10V, I _C =50mA	45			
	h _{FE(4)} *	V _{CE} =10V, I _C =100mA	40			
Collector-emitter saturation voltage	V _{CE(sat)1} *	I _C =1mA, I _B =0.1mA			0.4	V
	V _{CE(sat)2} *	I _C =10mA, I _B =1mA			0.5	V
	V _{CE(sat)3} *	I _C =50mA, I _B =5mA			0.75	V
Base-emitter saturation voltage	V _{BE(sat)} *	I _C =10mA, I _B =1mA			0.75	V
Collector output capacitance	C _{ob}	V _{CB} =20V, I _E =0, f=1MHz			7	pF
Emitter input capacitance	C _{ib}	V _{EB} =0.5V, I _C =0, f=1MHz			130	pF
Transition frequency	f _T	V _{CE} =20V, I _C =10mA, f=30MHz	50			MHz

*Pulse test: pulse width ≤300μs, duty cycles ≤ 2.0%.

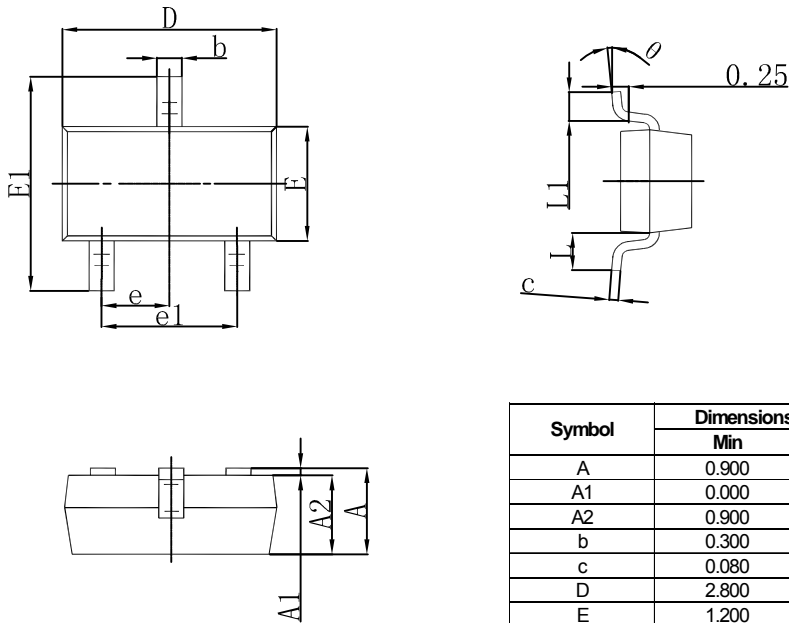
Typical Characteristics





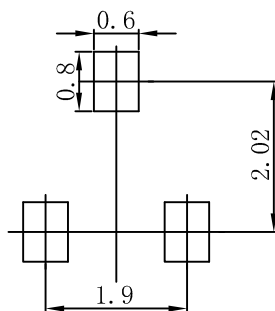


SOT-23 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

SOT-23 Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.



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